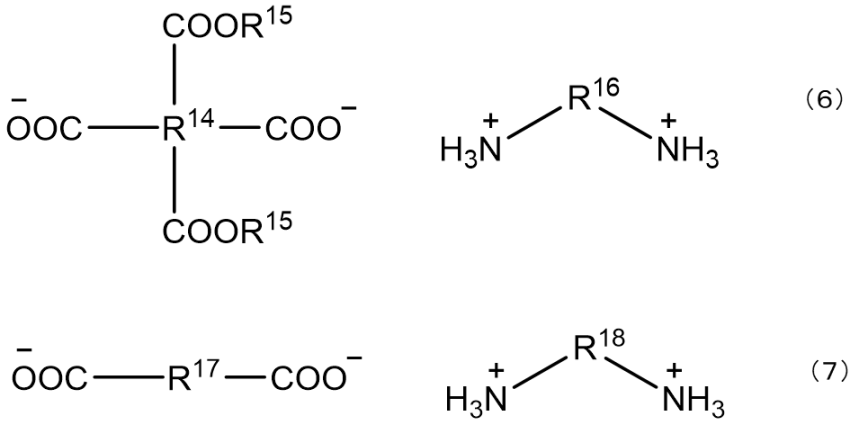
CLAIMS

[Claim 1]

A resin composition comprising: (A) a soluble resin, (B) an organic salt, and (C) a solvent, wherein (B) the organic salt is an organic salt formed from an organic compound having a carboxy group and an organic compound having an amino group,

wherein (B) the organic salt comprises an organic salt having a structure represented by the formula (6) or the formula (7):

[Chem. 1]



(6)

(7)

wherein in the formula (6), R^{14} represents a C_{4-40} tetravalent organic group; R^{15} represents a hydrogen atom or a C_{1-10} monovalent organic group; and R^{16} represents a C_{1-40} divalent organic group); and

wherein in the formula (7), R^{17} represents a C_{1-40} divalent organic group with the proviso that R^{17} contains neither a carboxy group nor a carboxylic acid ester group; and R^{18} represents a C_{1-40} divalent organic group,

and wherein the amount of (B) the organic salt is 0.01 to 10 parts by mass with respect to 100 parts by mass of (A) the soluble resin.

[Claim 2]

The resin composition according to claim 1, wherein (A) the soluble resin comprises at least one soluble resin selected from the group consisting of a polyimide, a polybenzoxazole, a precursor thereof, or a copolymer thereof.

[Claim 3]

The resin composition according to claims 1 or 2, further comprising (D) a photosensitizer.

[Claim 4]

The resin composition according to any one of claims 1 to 3, wherein (A) the soluble resin comprises at least one soluble resin selected from the group consisting of:

a polyimide having a structure represented by the formula (1);

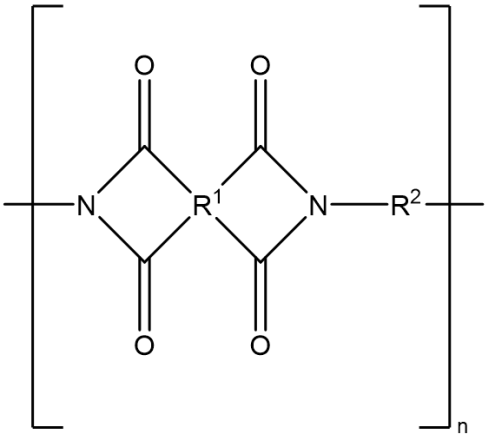
a polybenzoxazole having a structure represented by the formula (3);

a polyimide precursor having a structure represented by the formula (4), wherein g in the formula (4) is 2;

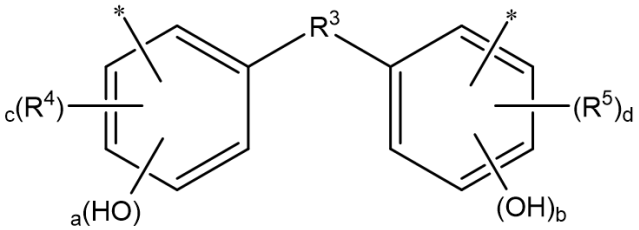
a polybenzoxazole precursor having a structure represented by the formula (4), wherein g in the formula (4) is 0; or

a copolymer thereof;

[Chem. 2]



(1)

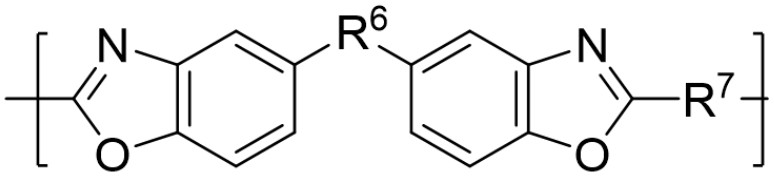


(2)

(wherein in the formula (1), R^1 represents a C_{4-40} tetravalent organic group; and R^2 represents a structure represented by the formula (2)) and

(wherein in the formula (2), R^3 represents a single bond, -O-, $-C(CH_3)_2-$, or $-C(CF_3)_2-$; R^4 and R^5 represent a C_{1-20} monovalent organic group; a and b each independently represent an integer of 1 to 4; c and d each independently represent an integer of 0 to 1; and the sign * represents a chemical bond);

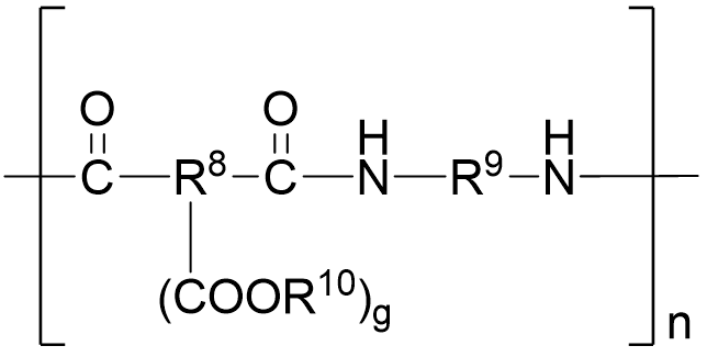
[Chem. 3]



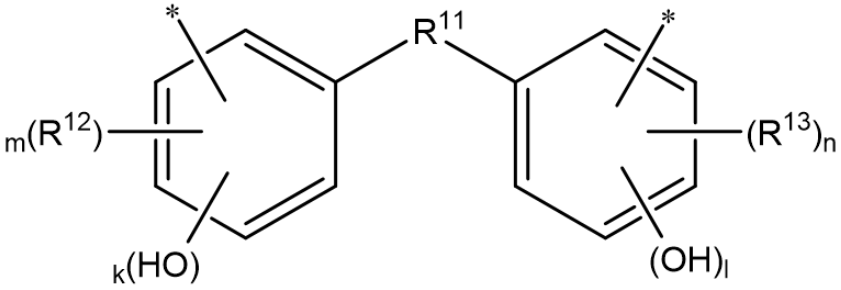
(3)

(wherein in the formula (3), R^6 represents a single bond, -O-, $-C(CH_3)_2-$, or $-C(CF_3)_2-$; and R^7 represents a C_{4-40} divalent organic group);

[Chem. 4]



(4)



(5)

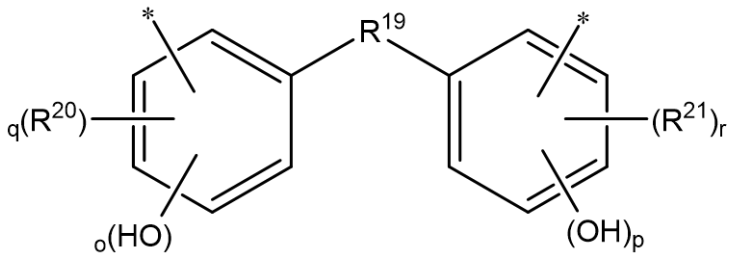
(wherein in the formula (4), R^8 represents a C_{4-40} divalent to tetravalent organic group; R^9 represents a structure represented by the formula (5); R^{10} represents a hydrogen atom or a C_{1-20} monovalent organic group; and g represents 0 or 2) and

(wherein in the formula (5), R^{11} represents a single bond, -O-, $-C(CH_3)_2-$, or $-C(CF_3)_2-$; R^{12} and R^{13} represent a C_{1-20} monovalent organic group; k and l each independently represent an integer of 1 to 4; m and n each independently represent an integer of 0 to 1; and the sign * represents a chemical bond).

[Claim 5]

The resin composition according to any one of claims 1 to 4, wherein R^{16} in the formula (6) and R^{18} in the formula (7) are each a structure represented by the formula (8):

[Chem. 5]



(8)

(wherein in the formula (8), R^{19} represents a single bond, -O-, $-C(CH_3)_2-$, or $-C(CF_3)_2-$; R^{20} and R^{21} represent a C_{1-20} monovalent organic group; o and p each independently represent an integer of 1 to 4; q and r each independently represent an integer of 0 to 1; and the sign * represents a chemical bond).

[Claim 6]

The resin composition according to claim 5, wherein R^{19} in the formula (8) is $-C(CF_3)_2-$.

[Claim 7]

A cured product obtained by curing the resin composition according to any one of claims 1 to 6.

[Claim 8]

An electronic component comprising the cured product according to claim 7.

[Claim 9]

A display device comprising the cured product according to claim 7.